

05-04-2000



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U.S. PATENT AND TRADEMARK OFFICE

MD 4-21-00

Case Docket No. 000502

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

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PATENTS ONLY

To the Assistant Commissioner for Patents.
Please record the attached original documents or copy thereof.

jc511 U.S. PTO
09/557085



1. Name of conveying parties:

Kohshi YOSHIMURA, Takeshi NISHIUCHI, Fumiaki KIKUI, Masahiro ASANO
and Takahiro ISOZAKI

Additional name(s) of conveying parties attached? Yes No XX

2. Name and address of receiving party:

Name: SUMITOMO SPECIAL METALS CO., LTD.

Street Address:

4-7-19, Kitahama, Chuo-ku
Osaka-shi, Osaka, Japan

Additional name(s) & address(es) attached? Yes No XX

09/55 7045

3. Nature of conveyance: **Assignment**

Execution Date: April 4, 2000

4. Title: **PROCESS FOR SEALING PORES IN MOLDED PRODUCT, AND BONDED
MAGNET WITH PORES SEALED BY THE PROCESS**

5. Application number(s) or patent number(s):

A. Patent Application No.(s) B. Patent No.(s)

If this document is being filed together with a new application, the execution date of the
application is: April 4, 2000

Additional numbers attached? Yes No XX

05/02/2000 HUIILLARI 00000005 09557085

04 FC:581

40.00 DP

PATENT
REEL: 010747 FRAME: 0214

6. Name and address of party to whom correspondence concerning document should be mailed:

Name: Armstrong, Westerman, Hattori,
McLeland & Naughton
Suite 1000
1725 K Street, N.W.
Washington, D.C. 20006

7. Total number of applications and patents involved: 1

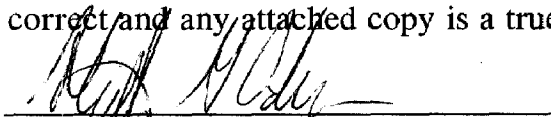
8. Total fee (37 CFR 3.41). \$ **40.00**

XX Check enclosed

9. Deposit Account No.: 01-2340

10. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.



Date April 21, 2000

Stephen G. Adrian
Reg. No.: 32,878

Total number of pages including cover sheet: 3

SGA/llf

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

(Insert ASSIGNEE's
Name(s) Address(es))

**Sumitomo Special Metals Co., Ltd. of 4-7-19, Kitahama, Chuo-ku,
Osaka-shi, Osaka Japan**

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of Invention)

**PROCESS FOR SEALING PORES IN MOLDED PRODUCT, AND
BONDED MAGNET WITH PORES SEALED BY THE PROCESS**

(*If the assignment is
being filed after the filing
of the application, this
section must be
completed)

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

*filed on _____, Serial No. _____.
(Armstrong, Westerman, Hattori, McLeland & Naughton is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefor on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with the application and any continuation, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

<u>Kohshi Yoshimura</u> (SIGNATURE)	<u>Kohshi YOSHIMURA</u> (TYPE NAME)	<u>April 4, 2000</u> (DATE)
<u>Takeshi Nishiuchi</u> (SIGNATURE)	<u>Takeshi NISHIUCHI</u> (TYPE NAME)	<u>April 4, 2000</u> (DATE)
<u>Fumiaki Kikui</u> (SIGNATURE)	<u>Fumiaki KIKUI</u> (TYPE NAME)	<u>April 4, 2000</u> (DATE)
<u>Masahiro Asano</u> (SIGNATURE)	<u>Masahiro ASANO</u> (TYPE NAME)	<u>April 4, 2000</u> (DATE)
<u>Takahiro Isozaki</u> (SIGNATURE)	<u>Takahiro ISOZAKI</u> (TYPE NAME)	<u>April 4, 2000</u> (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)

NO LEGALIZATION REQUIRED